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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

(1) Kazuo KANETANI, (2) Hiroaki NAMBU, (3)
 Kaname YAMASAKI, (4) Fumihiko ARAKAWA,
 (5) Takeshi KUSUNOKI and (6) Keiichi HIGETA

Additional names of conveying parties attached

2. Name and Address of Receiving Party(ies):

Name: **Hitachi, Ltd.**
 6, Kanda Surugadai 4-chome
 Chiyoda-ku, Tokyo, Japan

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Dates: (1)(2) Dec. 3, 2001; (3) Dec. 6,
 2001; and (4)(5)(6) Dec. 4, 2001

**Hitachi Device Engineering Co.
 Ltd.**
 3681, Hayano, Mobara-shi
 Chiba-ken 297-8581, Tokyo, Japan

4. (a) Patent Application Number(s):

If this document is being filed together with a new application, the
 execution dates of the application are:

(1)(2) Dec. 3, 2001; (3) Dec. 6, 2001; and (4)(5)(6) Dec.
 4, 2001

☐ Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence
 Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**

Address: **Reed Smith Hazel Thomas LLP**
 3110 Fairview Park Dr.
 Suite 1400
 Falls Church, Va. 22042

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: **\$40.00**
 (37 C.F.R. § 3.41)

- ☒ Enclosed.
☒ Authorized to be charged to deposit account.

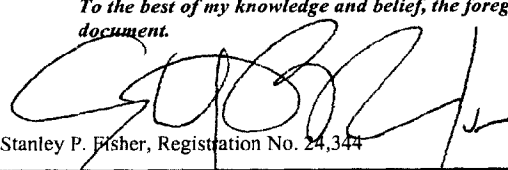
8. Deposit Account Number: 08-1480

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9. Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original
 document.


 Stanley P. Fisher, Registration No. 24,344

December 13, 2001

JUAN CARLOS A. MARQUEZ
 Registration No. 34,072

Total number of pages comprising cover sheet: 1

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ASSIGNMENT

(譲 渡 証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the below named inventor(s), citizens of Japan by HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3682, Hayano, Mobara-shi, Chiba, Japan, respectively, receipt of which is hereby acknowledged, we, the below named inventor(s), do hereby sell and assign to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., their successors and assigns, all our right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) <u>Kazuo Kanetani</u>	<u>12/3/2001</u>
2) <u>Hiroaki Nambu</u>	<u>12/3/2001</u>
3) <u>Kaname Yamasaki</u>	<u>12/6/2001</u>
4) <u>Fumihiko Arakawa</u>	<u>12 / 4 / 2001</u>
5) <u>Takeshi Kusunoki</u>	<u>12/4 / 2001</u>
6) <u>Keiichi Higeta</u>	<u>12 / 4 / 2001</u>
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____